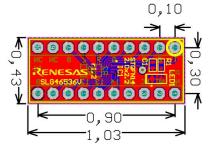


1. Description

The GreenPAK DIP Adapter is a small PCB that lets you adapt STQFN packages into a DIP footprint. This board can speed up your design prototyping and testing. This small board 0.43x1.03 inch uses 20 pins DIP footprint with 0.3 inch width. You can also use this adapter for prototyping by making STQFN package compatible with solder free breadboards.

2. Features

- Low cost
- Simplifies prototyping of SMT IC's
- Optional V_{DD} LED indicator
- Decoupling capacitor included
- Optional I²C pull-up resistor

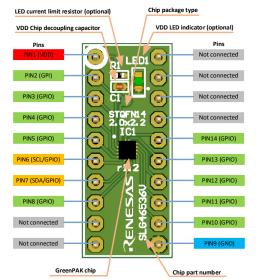


Note 1 All sizes in inches.

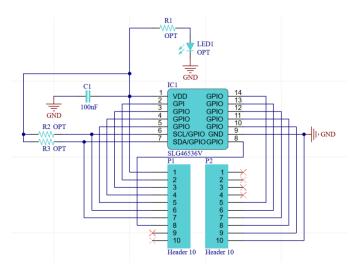
4. Bottom View

	Chip pin number	I2C pull up resistors (optional)
Pins		Pins
Not connected	Z 2	PIN1 (VDD)
Not connected		PIN2 (GPI)
Not connected		PIN3 (GPIO)
Not connected		PIN4 (GPIO)
PIN14 (GPIO)		PIN5 (GPIO)
PIN13 (GPIO)		PIN6 (SCL/GPIO)
PIN12 (GPIO)		PIN7 (SDA/GPIO)
PIN11 (GPIO)		PIN8 (GPIO)
PIN10 (GPIO)		Not connected
PIN9 (GND)		Not connected

3. Top View



5. Board Schematic



Revision 1.1

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